

FEATURES

- Double Side Cooling
- High Surge Capability

APPLICATIONS

- High Power Drives
- High Voltage Power Supplies
- Static Switches

VOLTAGE RATINGS

Part and Ordering Number	Repetitive Peak Voltages V_{DRM} and V_{RRM} V	Conditions
DCR2150C42	4200	$T_{vj} = -40^{\circ}\text{C}$ to 125°C , $I_{DRM} = I_{RRM} = 200\text{mA}$, $V_{DRM}, V_{RRM} t_p = 10\text{ms}$, $V_{DSM} \& V_{RSM} =$ $V_{DRM} \& V_{RRM} + 100\text{V}$ respectively
DCR2150C40	4000	
DCR2150C35	3500	
DCR2150C30	3000	

Lower voltage grades available.

ORDERING INFORMATION

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

DCR2150C42

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

KEY PARAMETERS

V_{DRM}	4200V
$I_{T(AV)}$	2150A
I_{TSM}	29000A
dV/dt^*	1500V/ μs
dI/dt	400A/ μs

* Higher dV/dt selections available

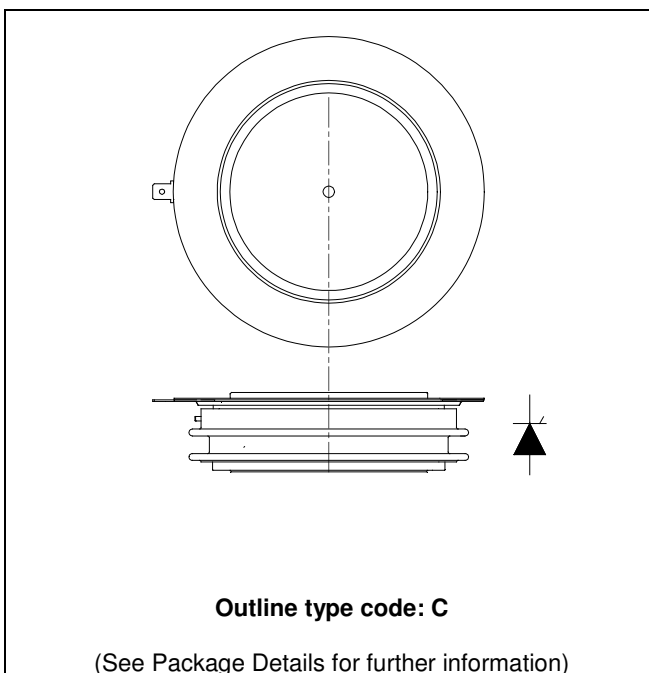


Fig. 1 Package outline

CURRENT RATINGS

$T_{case} = 60^{\circ}\text{C}$ unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
Double Side Cooled				
$I_{T(AV)}$	Mean on-state current	Half wave resistive load	2150	A
$I_{T(RMS)}$	RMS value	-	3377	A
I_T	Continuous (direct) on-state current	-	3280	A

SURGE RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
I_{TSM}	Surge (non-repetitive) on-state current	10ms half sine, $T_{case} = 125^{\circ}\text{C}$	29.0	kA
I^2t	I^2t for fusing	$V_R = 0$	4.2	MA^2s

THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
$R_{th(j-c)}$	Thermal resistance – junction to case	Double side cooled	DC	-	0.0101	$^{\circ}\text{C/W}$
		Single side cooled	Anode DC	-	0.0176	$^{\circ}\text{C/W}$
			Cathode DC	-	0.0239	$^{\circ}\text{C/W}$
$R_{th(c-h)}$	Thermal resistance – case to heatsink	Clamping force 37kN (with mounting compound)	Double side	-	0.0025	$^{\circ}\text{C/W}$
			Single side	-	0.005	$^{\circ}\text{C/W}$
T_{vj}	Virtual junction temperature	On-state (conducting)		-	135	$^{\circ}\text{C}$
		Reverse (blocking)		-	125	$^{\circ}\text{C}$
T_{stg}	Storage temperature range			-55	125	$^{\circ}\text{C}$
F_m	Clamping force			33.0	41.0	kN

DYNAMIC CHARACTERISTICS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
I _{RRM} /I _{DRM}	Peak reverse and off-state current	At V _{RRM} /V _{DRM} , T _{case} = 125 °C		-	200	mA
dV/dt	Max. linear rate of rise of off-state voltage	To 67% V _{DRM} , T _j = 125 °C, gate open		-	1500	V/μs
dI/dt	Rate of rise of on-state current	From 67% V _{DRM} to 2x I _{T(AV)}	Repetitive 50Hz	-	200	A/μs
		Gate source 30V, 10Ω, t _r < 0.5μs, T _j = 125 °C	Non-repetitive	-	400	A/μs
V _{T(TO)}	Threshold voltage – Low level	500A to 2000A at T _{case} = 125 °C		-	0.9	V
	Threshold voltage – High level	2000A to 7000A at T _{case} = 125 °C		-	1.08	V
r _T	On-state slope resistance – Low level	500A to 2000A at T _{case} = 125 °C		-	0.36	mΩ
	On-state slope resistance – High level	2000A to 7000A at T _{case} = 125 °C		-	0.265	mΩ
t _{gd}	Delay time	V _D = 67% V _{DRM} , gate source 30V, 10Ω t _r = 0.5μs, T _j = 25 °C		TBD	TBD	μs
t _q	Turn-off time	T _j = 125 °C, V _R = 200V, dI/dt = 1A/μs, dV _{DR} /dt = 20V/μs linear		250	500	μs
Q _S	Stored charge	I _T = 2000A, T _j = 125 °C, dI/dt – 1A/μs,		1000	3000	μC
I _L	Latching current	T _j = 25 °C, V _D = 5V		-	3	A
I _H	Holding current	T _j = 25 °C, R _{G-K} = ∞, I _{TM} = 500A, I _T = 5A		-	300	mA

GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
V_{GT}	Gate trigger voltage	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	1.5	V
V_{GD}	Gate non-trigger voltage	At $V_{DRM}, T_{case} = 125^{\circ}C$	TBD	V
I_{GT}	Gate trigger current	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	250	mA
I_{GD}	Gate non-trigger current	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	TBD	mA

CURVES

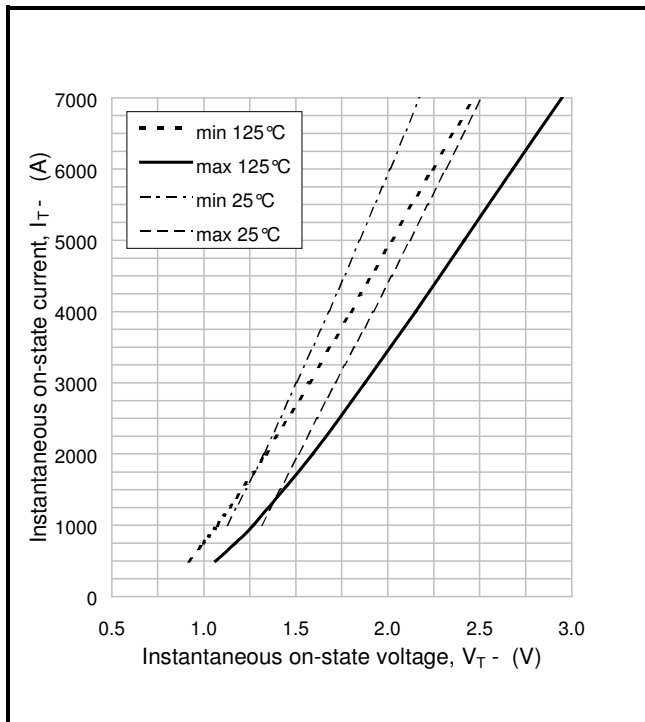


Fig.2 Maximum & minimum on-state characteristics

V_{TM} EQUATION

$$V_{TM} = A + B \ln(I_T) + C \cdot I_T + D \cdot \sqrt{I_T}$$

Where $A = 0.137154$

$B = 0.132631$

$C = 0.000248$

$D = -0.001126$

these values are valid for $T_j = 125^{\circ}C$ for I_T 100A to 7000A

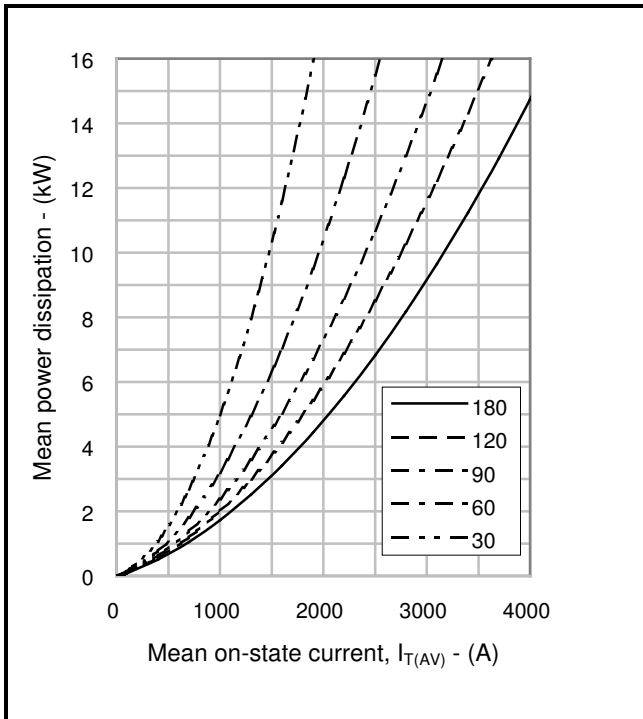


Fig.3 On-state power dissipation – sine wave

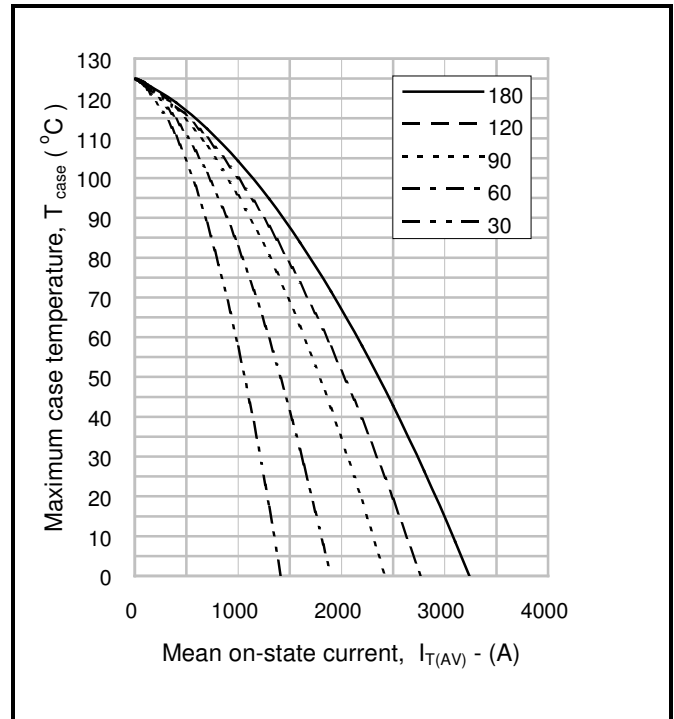


Fig.4 Maximum permissible case temperature, double side cooled – sine wave

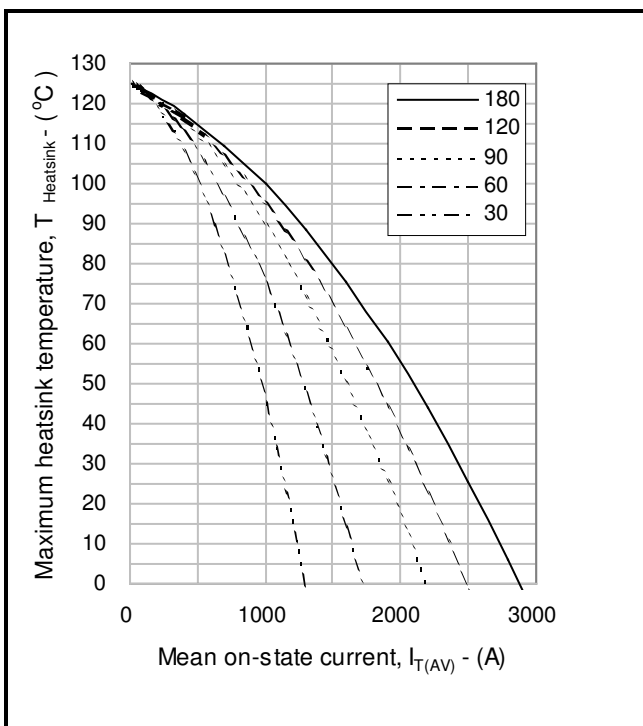


Fig.5 Maximum permissible heatsink temperature, double side cooled – sine wave

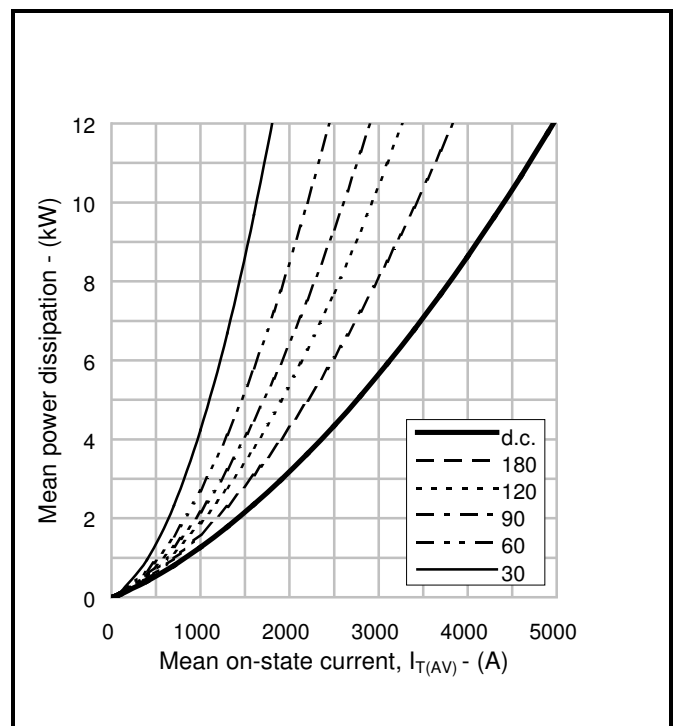


Fig.6 On-state power dissipation – rectangular wave

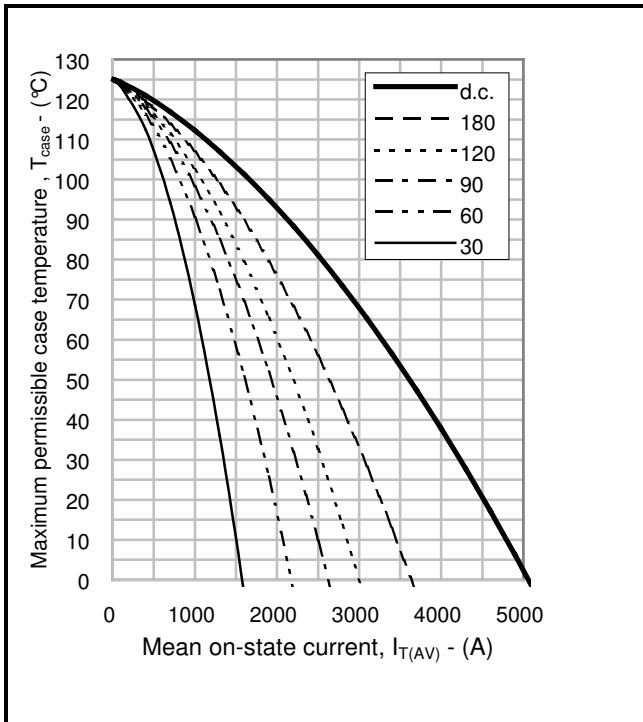


Fig.7 Maximum permissible case temperature, double side cooled – rectangular wave

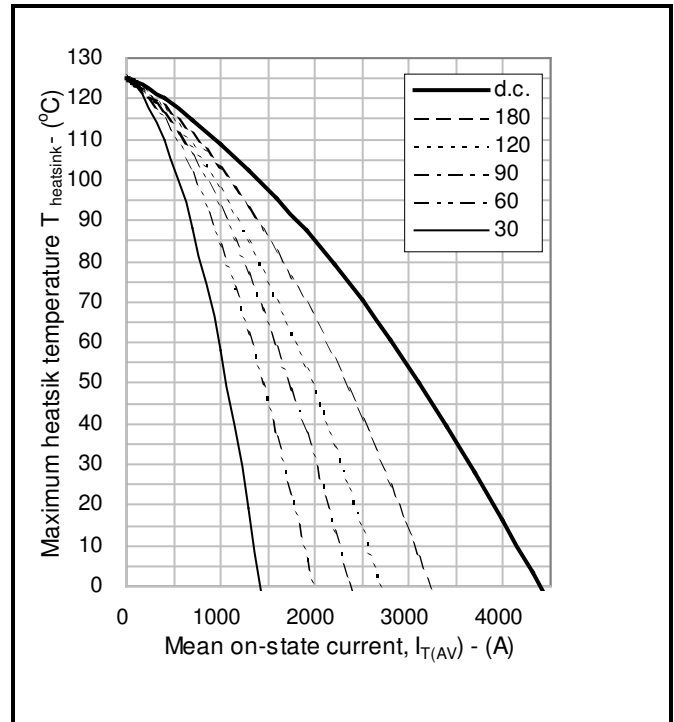


Fig.8 Maximum permissible heatsink temperature, double side cooled – rectangular wave

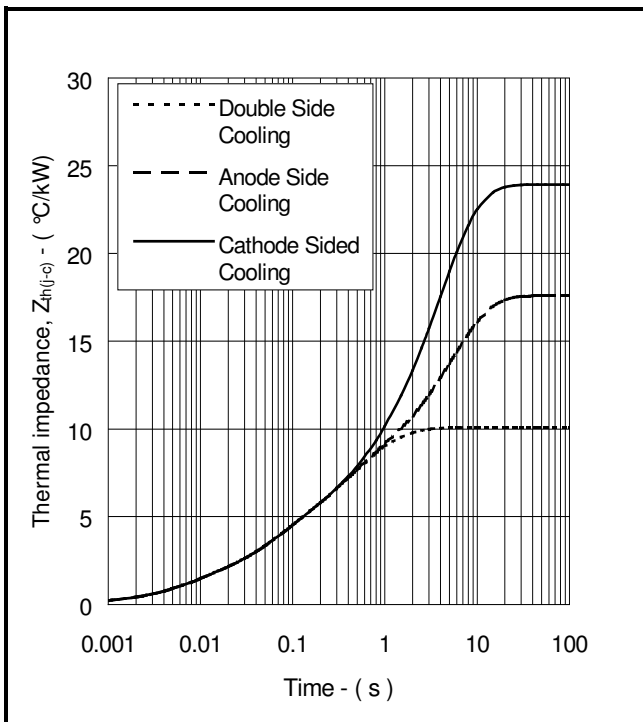


Fig.9 Maximum (limit) transient thermal impedance – junction to case (°C/kW)

		1	2	3	4
Double side cooled	$R_{th(j-c)}$ (°C/kW)	1.1043	2.576	4.5096	1.9009
	T_1 (s)	0.006176	0.0517916	0.3820376	1.06
Anode side cooled	$R_{th(j-c)}$ (°C/kW)	1.0977	2.4566	4.0469	9.9994
	T_1 (s)	0.006153	0.050142	0.3129407	5.27
Cathode side cooled	$R_{th(j-c)}$ (°C/kW)	1.1519	2.8926	2.4064	17.4793
	T_1 (s)	0.006389	0.0582953	0.3775516	3.97

$$Z_{th} = \sum [R_i \times (1 - \exp. (-t/t_i))] \quad [1]$$

$\Delta R_{th(j-c)}$ Conduction

Tables show the increments of thermal resistance $R_{th(j-c)}$ when the device operates at conduction angles other than d.c.

Double side cooling			Anode Side Cooling			Cathode Sided Cooling		
$\Delta Z_{th} (z)$			$\Delta Z_{th} (z)$			$\Delta Z_{th} (z)$		
θ°	sine	rect.	θ°	sine	rect.	θ°	sine	rect.
180	1.95	1.26	180	1.95	1.26	180	1.95	1.26
120	2.32	1.89	120	2.32	1.89	120	2.31	1.88
90	2.74	2.27	90	2.74	2.27	90	2.72	2.26
60	3.14	2.70	60	3.14	2.70	60	3.12	2.68
30	3.46	3.19	30	3.46	3.19	30	3.43	3.17
15	3.61	3.47	15	3.62	3.47	15	3.58	3.44

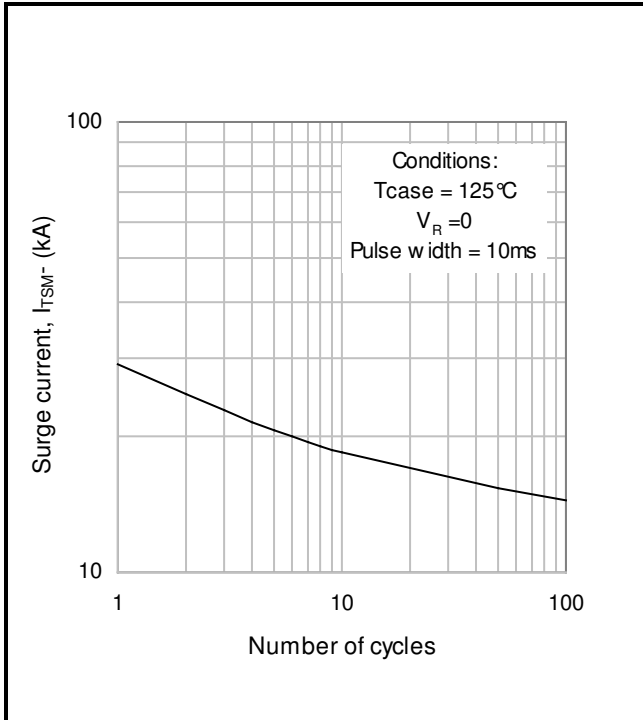


Fig.10 Multi-cycle surge current

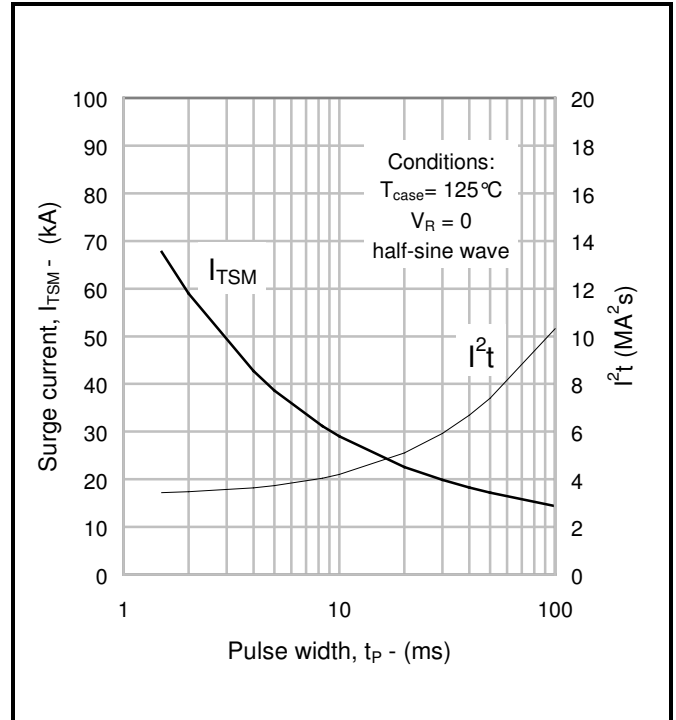


Fig.11 Single-cycle surge current

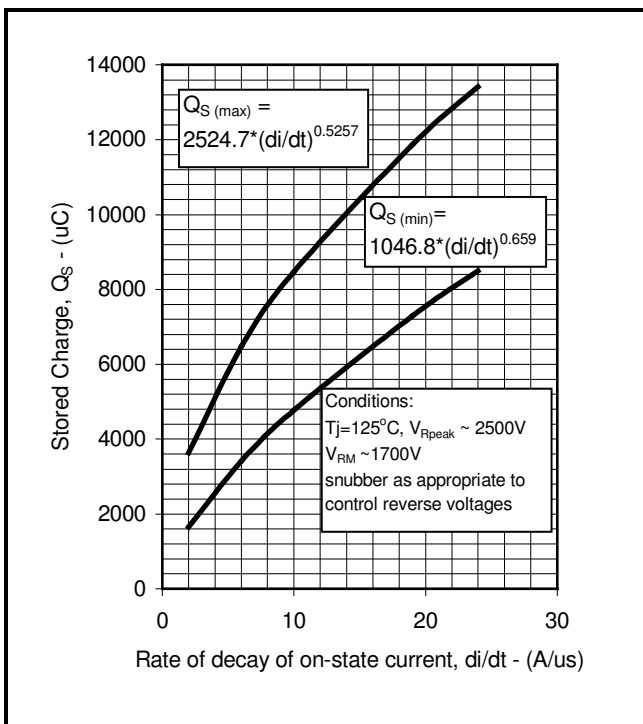


Fig.12 Reverse recovery charge

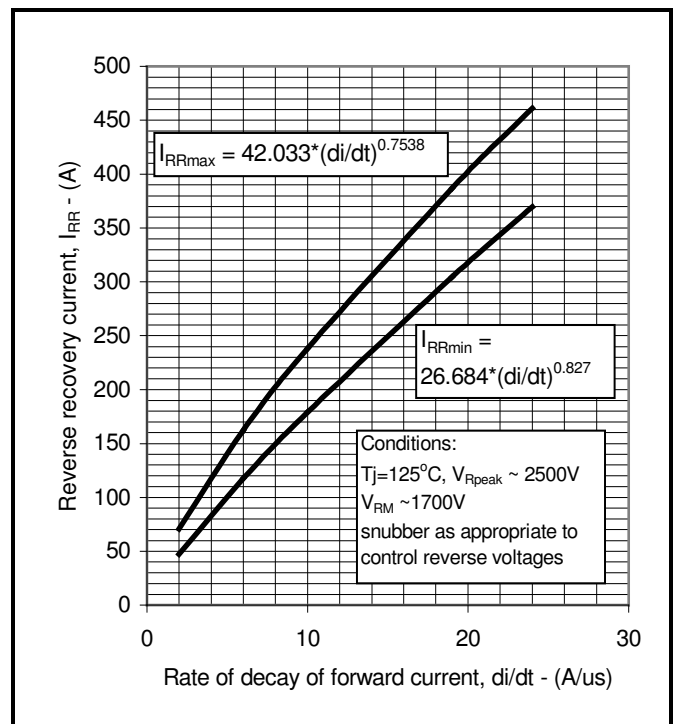


Fig.13 Reverse recovery current

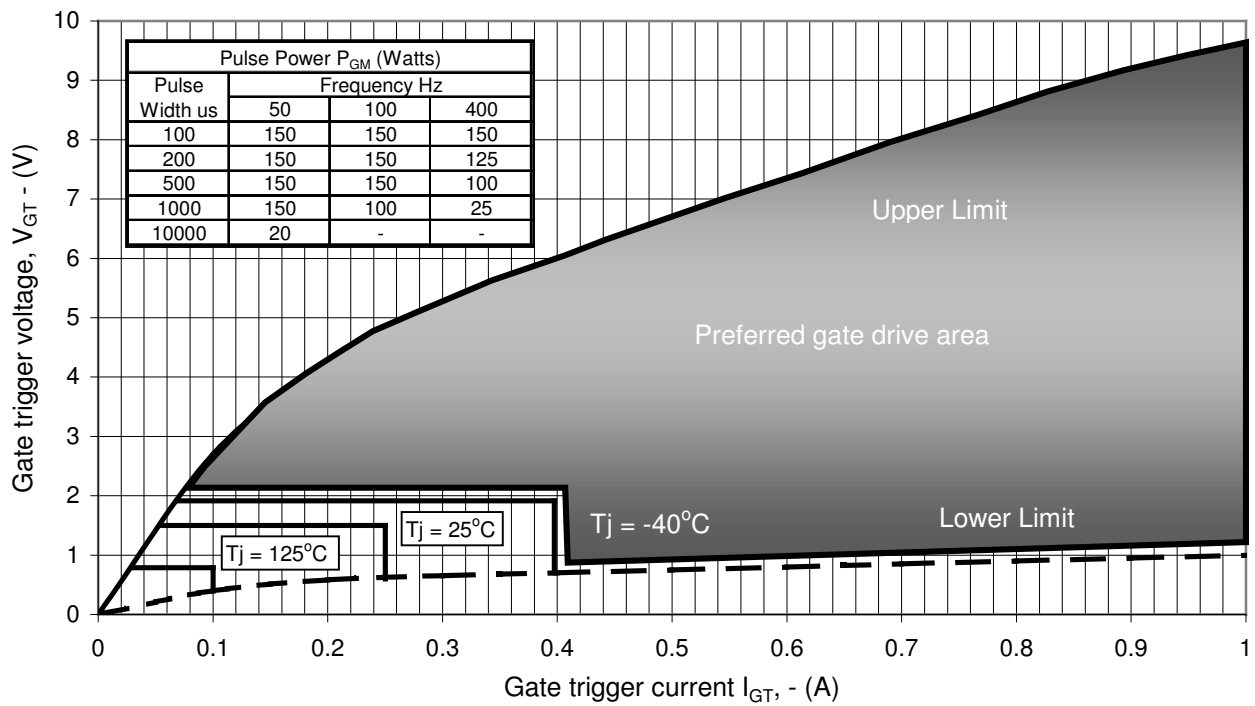


Fig14 Gate Characteristics

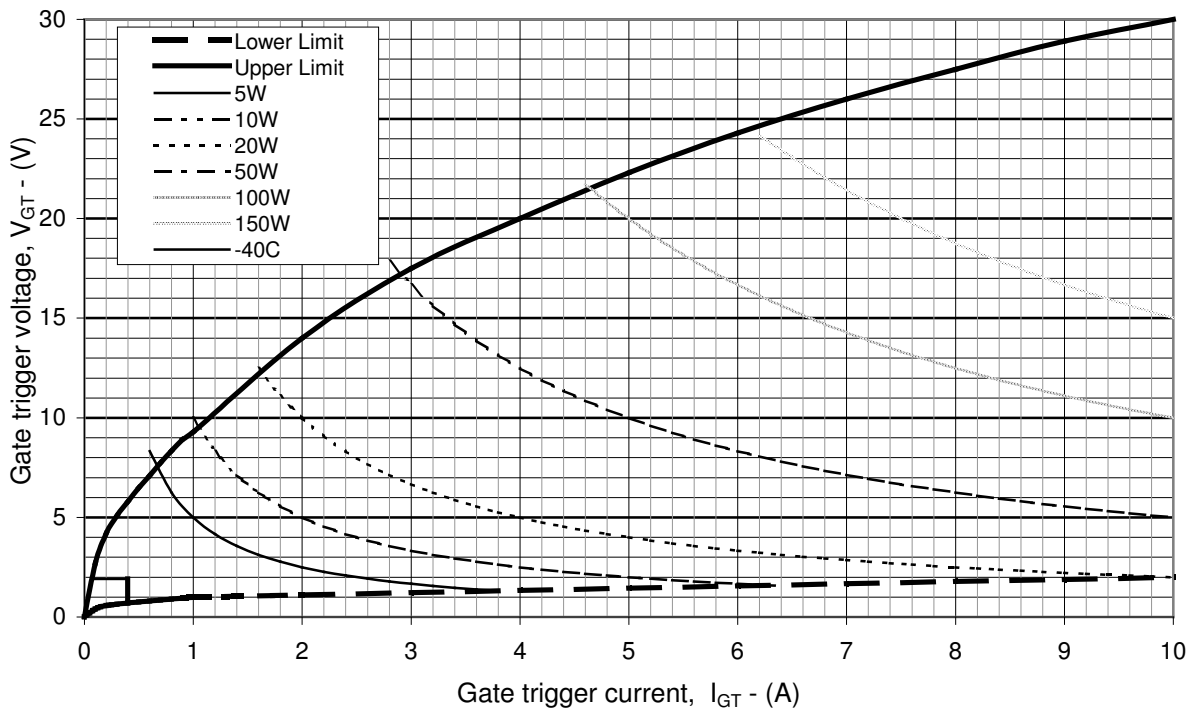


Fig. 15 Gate characteristics

PACKAGE DETAILS

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.

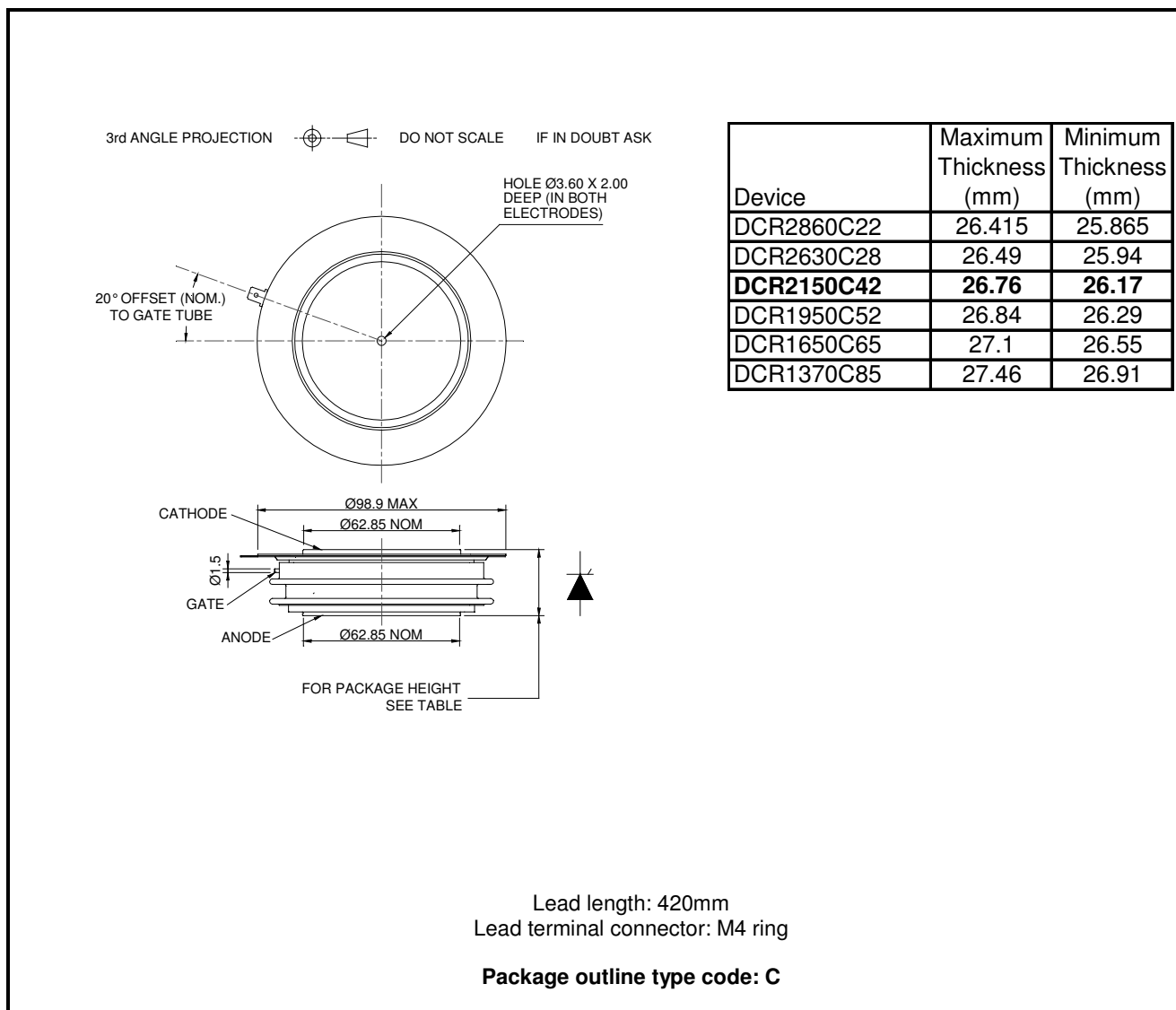


Fig.16 Package outline

POWER ASSEMBLY CAPABILITY

The Power Assembly group was set up to provide a support service for those customers requiring more than the basic semiconductor, and has developed a flexible range of heatsink and clamping systems in line with advances in device voltages and current capability of our semiconductors.

We offer an extensive range of air and liquid cooled assemblies covering the full range of circuit designs in general use today. The Assembly group offers high quality engineering support dedicated to designing new units to satisfy the growing needs of our customers.

Using the latest CAD methods our team of design and applications engineers aim to provide the Power Assembly Complete Solution (PACs).

HEATSINKS

The Power Assembly group has its own proprietary range of extruded aluminium heatsinks which have been designed to optimise the performance of Dynex semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest sales representative or Customer Services.

Stresses above those listed in this data sheet may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed.



<http://www.dynexsemi.com>

e-mail: power_solutions@dynexsemi.com

**HEADQUARTERS OPERATIONS
DYNEX SEMICONDUCTOR LTD**
Doddington Road, Lincoln
Lincolnshire, LN6 3LF. United Kingdom.
Tel: +44(0)1522 500500
Fax: +44(0)1522 500550

CUSTOMER SERVICE
Tel: +44(0)1522 502753 / 502901. Fax: +44(0)1522 500020

© Dynex Semiconductor 2003 TECHNICAL DOCUMENTATION – NOT FOR
RESALE. PRODUCED IN UNITED KINGDOM.

This publication is issued to provide information only which (unless agreed by the Company in writing) may not be used, applied or reproduced for any purpose nor form part of any order or contract nor to be regarded as a representation relating to the products or services concerned. No warranty or guarantee express or implied is made regarding the capability, performance or suitability of any product or service. The Company reserves the right to alter without prior notice the specification, design or price of any product or service. Information concerning possible methods of use is provided as a guide only and does not constitute any guarantee that such methods of use will be satisfactory in a specific piece of equipment. It is the user's responsibility to fully determine the performance and suitability of any equipment using such information and to ensure that any publication or data used is up to date and has not been superseded. These products are not suitable for use in any medical products whose failure to perform may result in significant injury or death to the user. All products and materials are sold and services provided subject to the Company's conditions of sale, which are available on request.

All brand names and product names used in this publication are trademarks, registered trademarks or trade names of their respective owners.